

PATENT ABSTRACTS OF JAPAN

(11)Publication number : **05-013322**

(43)Date of publication of application : **22.01.1993**

(51)Int.Cl. **H01L 21/027**
B05C 11/08
G03F 7/16
H01L 21/31

(21)Application number : **03-167975**

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(22)Date of filing : **09.07.1991**

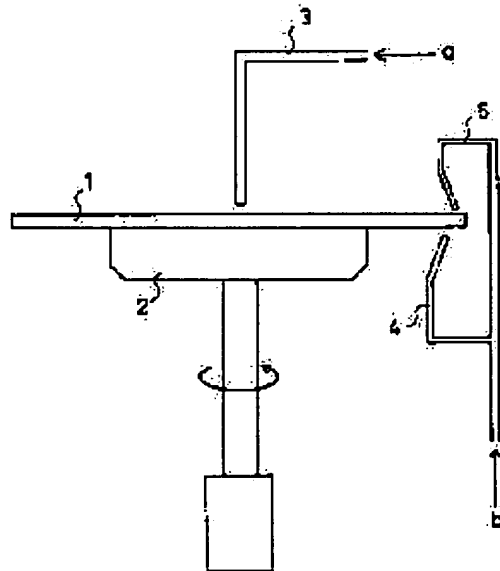
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(54) FILM SOLVENT APPLICATION DEVICE

(57)Abstract:

PURPOSE: To prevent the occurrence of the particles after baking process and improve the quality of the chip made in a semiconductor substrate by preventing the swelling of the film solvent at the surface margin of a semiconductor substrate.

CONSTITUTION: A surface cleaning nozzle 5, which jets out cleaning liquid to the surface margin of a semiconductor substrate 1, is provided being branched off from a rear cleaning nozzle 4.



LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]